The LMC7660 is a CMOS voltage converter capable of converting a positive voltage in the range of +1.5V to +10V to the corresponding negative voltage of −1.5V to −10V. The LMC7660 is a pin-for-pin replacement for the industry-standard 7660. The converter features: operation over full temperature and voltage range without need for an external diode, low quiescent current, and high power efficiency.

The LMC7660 uses its built-in oscillator to switch 4 power MOS switches and charge two inexpensive electrolytic capacitors.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet. All trademarks are the property of their respective owners.
These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

**ABSOLUTE MAXIMUM RATINGS**

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Conditions</th>
<th>Limit (μA)</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Supply Voltage</strong></td>
<td>DC to (V+ + 0.3V)</td>
<td>10.5V</td>
</tr>
<tr>
<td><strong>Input Voltage on Pin 6, γ</strong></td>
<td>DC to (V+ + 0.3V)</td>
<td>−0.3V to</td>
</tr>
<tr>
<td></td>
<td></td>
<td>V+ &lt; 5.5V</td>
</tr>
<tr>
<td></td>
<td></td>
<td>(V+ − 5.5V) to (V+ + 0.3V) for V+ &gt; 5.5V</td>
</tr>
<tr>
<td><strong>Current into Pin 6</strong></td>
<td>DC</td>
<td>20 μA</td>
</tr>
<tr>
<td><strong>Output Short Circuit Duration</strong></td>
<td>(V+ ≤ 5.5V)</td>
<td>Continuous</td>
</tr>
<tr>
<td><strong>Power Dissipation</strong></td>
<td>PDIP Package</td>
<td>1.4W</td>
</tr>
<tr>
<td></td>
<td>SOIC Package</td>
<td>0.6W</td>
</tr>
<tr>
<td><strong>T J Max</strong></td>
<td></td>
<td>150°C</td>
</tr>
<tr>
<td><strong>θ JA</strong></td>
<td>PDIP Package</td>
<td>90°C/W</td>
</tr>
<tr>
<td></td>
<td>SOIC Package</td>
<td>160°C/W</td>
</tr>
<tr>
<td><strong>Storage Temp. Range</strong></td>
<td>−65°C ≤ T ≤ 150°C</td>
<td></td>
</tr>
<tr>
<td><strong>Lead Temperature</strong></td>
<td>(Soldering, 5 sec.)</td>
<td>260°C</td>
</tr>
<tr>
<td><strong>ESD Tolerance</strong> (±2000V)</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

(1) Absolute Maximum ratings indicate limits beyond which damage to the device may occur. DC and AC electrical specifications do not apply when operating the device beyond its rated operating conditions. See Note (1) under Electrical Characteristics for conditions.
(2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.
(3) Connecting any input terminal to voltages greater than V+ or less than ground may cause destructive latchup. It is recommended that no inputs from sources operating from external supplies be applied prior to “power-up” of the LMC7660.
(4) For operation at elevated temperature, these devices must be derated based on a thermal resistance of θ JA and T J max, T j = T A + θ JA PD.
(5) The test circuit consists of the human body model of 100 pF in series with 1500 Ω.

**ELECTRICAL CHARACTERISTICS**

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Type</th>
<th>LMC7660IN/ LMCM7660IM</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>I s</td>
<td>Supply Current</td>
<td>R L = ∞</td>
<td>120</td>
<td>200</td>
<td>µA</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td></td>
<td>400</td>
<td>max</td>
</tr>
<tr>
<td>V+H</td>
<td>Supply Voltage</td>
<td>R L = 10 kΩ, Pin 6 Open</td>
<td>3 to 10</td>
<td>3 to 10</td>
<td>V</td>
</tr>
<tr>
<td></td>
<td>Range High</td>
<td>Voltage Efficiency ≥ 90%</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td></td>
<td>3 to 10</td>
<td></td>
</tr>
<tr>
<td>V+L</td>
<td>Supply Voltage</td>
<td>R L = 10 kΩ, Pin 6 to Gnd.</td>
<td>1.5 to 3.5</td>
<td>1.5 to 3.5</td>
<td>V</td>
</tr>
<tr>
<td></td>
<td>Range Low</td>
<td>Voltage Efficiency ≥ 90%</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td></td>
<td>1.5 to 3.5</td>
<td></td>
</tr>
</tbody>
</table>

(1) Boldface numbers apply at temperature extremes. All other numbers apply at T A = 25°C, V+ = 5V, C osc = 0, and apply for the LMC7660 unless otherwise specified. Test circuit is shown in Figure 1 .
(2) Limits at room temperature are specified and 100% production tested. Limits in boldface are specified over the operating temperature range (but not 100% tested), and are not used to calculate outgoing quality levels.
(3) The LMC7660 can operate without an external diode over the full temperature and voltage range. The LMC7660 can also be used with the external diode Dx, when replacing previous 7660 designs.
### ELECTRICAL CHARACTERISTICS<sup>(1)</sup> (continued)

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Typ</th>
<th>LMC7660IN/</th>
<th>LMC7660IM</th>
<th>Units</th>
<th>Limits</th>
</tr>
</thead>
<tbody>
<tr>
<td>R&lt;sub&gt;out&lt;/sub&gt;</td>
<td>Output Source Resistance</td>
<td>I&lt;sub&gt;L&lt;/sub&gt; = 20 mA</td>
<td>55</td>
<td>100</td>
<td>120</td>
<td>Ω</td>
<td>max</td>
</tr>
<tr>
<td></td>
<td></td>
<td>V = 2V, I&lt;sub&gt;L&lt;/sub&gt; = 3 mA</td>
<td>110</td>
<td>200</td>
<td>300</td>
<td>Ω</td>
<td>max</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Pin 6 Short to Gnd.</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>F&lt;sub&gt;osc&lt;/sub&gt;</td>
<td>Oscillator Frequency</td>
<td></td>
<td>10</td>
<td></td>
<td></td>
<td>kHz</td>
<td></td>
</tr>
<tr>
<td>P&lt;sub&gt;eff&lt;/sub&gt;</td>
<td>Power Efficiency</td>
<td>R&lt;sub&gt;L&lt;/sub&gt; = 5 kΩ</td>
<td>97</td>
<td>95</td>
<td>90</td>
<td>%</td>
<td>min</td>
</tr>
<tr>
<td>V&lt;sub&gt;0 eff&lt;/sub&gt;</td>
<td>Voltage Conversion Efficiency</td>
<td>R&lt;sub&gt;L&lt;/sub&gt; = ∞</td>
<td>99.9</td>
<td>97</td>
<td>95</td>
<td>%</td>
<td>min</td>
</tr>
<tr>
<td>I&lt;sub&gt;osc&lt;/sub&gt;</td>
<td>Oscillator Sink or Source Current</td>
<td>Pin 7 = Gnd. or V&lt;sup&gt;+&lt;/sup&gt;</td>
<td>3</td>
<td></td>
<td></td>
<td>μA</td>
<td></td>
</tr>
</tbody>
</table>

Figure 1. LMC7660 Test Circuit
TYPICAL PERFORMANCE CHARACTERISTICS

Figure 2. OSC Freq. vs OSC Capacitance

Figure 3. $V_{out}$ vs $I_{out} @ V^+ = 2V$

Figure 4. $V_{out}$ vs Load Current ($V^+ = 5V$)

Figure 5. Supply Current & Power Efficiency vs Load Current ($V^+ = 2V$)

Figure 6. Supply Current & Power Efficiency vs Load Current ($V^+ = 5V$)

Figure 7. Output Source Resistance as a Function of Temperature
ypical Performance Characteristics (continued)

Unloaded Oscillator Frequency as a Function of Temperature

Temperature (°C)

Oscillator Frequency (kHz)

Figure 8.

Output Resistance (Ω)

Supply Voltage (V+)

Figure 9.

P_{eff} vs Oscillator Frequency @ V+ = 5V

Power Efficiency (%)

Oscillator Frequency (Hz)

Figure 10.
CIRCUIT DESCRIPTION

The LMC7660 contains four large CMOS switches which are switched in a sequence to provide supply inversion \( V_{out} = -V_{in} \). Energy transfer and storage are provided by two inexpensive electrolytic capacitors. Figure 11 shows how the LMC7660 can be used to generate \(-V^+\) from \( V^+\). When switches S1 and S3 are closed, \( C_p \) charges to the supply voltage \( V^+\). During this time interval, switches S2 and S4 are open. After \( C_p \) charges to \( V^+\), S1 and S3 are opened, S2 and S4 are then closed. By connecting S2 to ground, \( C_p \) develops a voltage \(-V^+/2\) on \( C_r \). After a number of cycles \( C_r \) will be pumped to exactly \(-V^+\). This transfer will be exact assuming no load on \( C_r \), and no loss in the switches.

In the circuit of Figure 11, S1 is a P-channel device and S2, S3, and S4 are N-channel devices. Because the output is biased below ground, it is important that the p-wells of S3 and S4 never become forward biased with respect to either their sources or drains. A substrate logic circuit specifies that these p-wells are always held at the proper voltage. Under all conditions S4 p-well must be at the lowest potential in the circuit. To switch off S4, a level translator generates \( V_{GS4} = 0V\), and this is accomplished by biasing the level translator from the S4 p-well.

An internal RC oscillator and \( \div 2 \) circuit provide timing signals to the level translator. The built-in regulator biases the oscillator and divider to reduce power dissipation on high supply voltage. The regulator becomes active at about \( V^+ = 6.5V\). Low voltage operation can be improved if the LV pin is shorted to ground for \( V^+ \leq 3.5V\). For \( V^+ \geq 3.5V\), the LV pin must be left open to prevent damage to the part.

POWER EFFICIENCY AND RIPPLE

It is theoretically possible to approach 100% efficiency if the following conditions are met:
1. The drive circuitry consumes little power.
2. The power switches are matched and have low \( R_{on} \).
3. The impedance of the reservoir and pump capacitors are negligibly small at the pumping frequency.

The LMC7660 closely approaches 1 and 2 above. By using a large pump capacitor \( C_p \), the charge removed while supplying the reservoir capacitor is small compared to \( C_p \)'s total charge. Small removed charge means small changes in the pump capacitor voltage, and thus small energy loss and high efficiency. The energy loss by \( C_p \) is:

\[
E = \frac{1}{2}C_p (V1^2 - V2^2) \tag{1}
\]

By using a large reservoir capacitor, the output ripple can be reduced to an acceptable level. For example, if the load current is 5 mA and the accepted ripple is 200 mV, then the reservoir capacitor can omit approximately be calculated from:

\[
C_r = \frac{C_r \times \frac{V_{ripple \ p-p}}{4/Fosc}}{\frac{dv}{dt}} \approx \frac{0.5 \text{ mA}}{0.5 \text{V/ms}} = 10 \mu F \tag{2}
\]

PRECAUTIONS

1. Do not exceed the maximum supply voltage or junction temperature.
2. Do not short pin 6 (LV terminal) to ground for supply voltages greater than 3.5V.
3. Do not short circuit the output to \( V^+\).
4. External electrolytic capacitors \( C_r \) and \( C_p \) should have their polarities connected as shown in Figure 1.

REPLACING PREVIOUS 7660 DESIGNS

To prevent destructive latchup, previous 7660 designs require a diode in series with the output when operated at elevated temperature or supply voltage. Although this prevented the latchup problem of these designs, it lowered the available output voltage and increased the output series resistance.

The TI LMC7660 has been designed to solve the inherent latch problem. The LCM7660 can operate over the entire supply voltage and temperature range without the need for an output diode. When replacing existing designs, the LMC7660 can be operated with diode Dx.
TYPICAL APPLICATIONS

CHANGING OSCILLATOR FREQUENCY

It is possible to dramatically reduce the quiescent operating current of the LMC7660 by lowering the oscillator frequency. The oscillator frequency can be lowered from a nominal 10 kHz to several hundred hertz, by adding a slow-down capacitor $C_{osc}$ (Figure 12). As shown in the Typical Performance Curves the supply current can be lowered to the 10 $\mu$A range. This low current drain can be extremely useful when used in $\mu$Power and battery back-up equipment. It must be understood that the lower operating frequency and supply current cause an increased impedance of $C_r$ and $C_p$. The increased impedance, due to a lower switching rate, can be offset by raising $C_r$ and $C_p$ until ripple and load current requirements are met.

SYNCHRONIZING TO AN EXTERNAL CLOCK

Figure 13 shows an LMC7660 synchronized to an external clock. The CMOS gate overrides the internal oscillator when it is necessary to switch faster or reduce power supply interference. The external clock still passes through the ÷2 circuit in the 7660, so the pumping frequency will be $\frac{1}{2}$ the external clock frequency.
LOWERING OUTPUT IMPEDANCE

Paralleling two or more LMC7660's lowers output impedance. Each device must have its own pumping capacitor $C_p$, but the reservoir capacitor $C_r$ is shared as depicted in Figure 14. The composite output resistance is:

$$R_{out} = \frac{R_{out \ of \ one \ LMC7660}}{\text{Number of devices}}$$

(INCREASING OUTPUT VOLTAGE

Stacking the LMC7660s is an easy way to produce a greater negative voltage. It should be noted that the input current required for each stage is twice the load current on that stage as shown in Figure 15. The effective output resistance is approximately the sum of the individual $R_{out}$ values, and so only a few levels of multiplication can be used.

It is possible to generate $-15V$ from $+5V$ by connecting the second 7660's pin 8 to $+5V$ instead of ground as shown in Figure 16. Note that the second 7660 sees a full $20V$ and the input supply should not be increased beyond $+5V$. 

![Figure 14. Lowering Output Resistance by Paralleling Devices](image1)

![Figure 15. Higher Voltage by Cascade](image2)

![Figure 16. Getting $-15V$ from $+5V$](image3)
SPLIT \( V^+ \) IN HALF

Figure 17 is one of the more interesting applications for the LMC7660. The circuit can be used as a precision voltage divider (for very light loads), alternately it is used to generate a \( \frac{1}{2} \) supply point in battery applications. In the \( \frac{1}{2} \) cycle when S1 and S3 are closed, the supply voltage divides across the capacitors in a conventional way proportional to their value. In the \( \frac{1}{2} \) cycle when S2 and S4 are closed, the capacitors switch from a series connection to a parallel connection. This forces the capacitors to have the same voltage; the charge redistributes to maintain precisely \( V^+ / 2 \), across \( C_p \) and \( C_r \). In this application all devices are only \( V^+ / 2 \), and the supply voltage can be raised to 20V giving exactly 10V at \( V_{out} \).

GETTING UP … AND DOWN

The LMC7660 can also be used as a positive voltage multiplier. This application, shown in Figure 18, requires 2 additional diodes. During the first \( \frac{1}{2} \) cycle S2 charges \( C_p1 \) through D1; D2 is reverse biased. In the next \( \frac{1}{2} \) cycle S2 is open and S1 is closed. Since \( C_p1 \) is charged to \( V^+ - V_{D1} \) and is referenced to \( V^+ \) through S1, the junction of D1 and D2 is at \( V^+ + (V^+ - V_{D1}) \). D1 is reverse biased in this interval. This application uses only two of the four switches in the 7660. The other two switches can be put to use in performing a negative conversion at the same time as shown in Figure 19. In the \( \frac{1}{2} \) cycle that D1 is charging \( C_p1 \), \( C_p2 \) is connected from ground to \( -V_{out} \) via S2 and S4, and \( C_p2 \) is storing \( C_p2 \)'s charge. In the interval that S1 and S3 are closed, \( C_p1 \) pumps the junction of D1 and D2 above \( V^+ \), while \( C_p2 \) is refreshed from \( V^+ \).

Figure 17. Split \( V^+ \) in Half

Figure 18. Positive Voltage Multiplier

Figure 19. Combined Negative Converter and Positive Multiplier
THERMOMETER SPANS 180°C

Using the combined negative and positive multiplier of Figure 20 with an LM35 it is possible to make a µPower thermometer that spans a 180°C temperature range. The LM35 temperature sensor has an output sensitivity of 10 mV/°C, while drawing only 50 µA of quiescent current. In order for the LM35 to measure negative temperatures, a pull down to a negative voltage is required. Figure 20 shows a thermometer circuit for measuring temperatures from −55°C to +125°C and requiring only two 1.5V cells. End of battery life can be extended by replacing the up converter diodes with Schottky's.

REGULATING −V<sub>OUT</sub>

It is possible to regulate the output of the LMC7660 and still maintain µPower performance. This is done by enclosing the LMC7660 in a loop with a LP2951. The circuit of Figure 21 will regulate V<sub>out</sub> to −5V for I<sub>L</sub> = 10 mA, and V<sub>in</sub> = 6V. For V<sub>in</sub> > 7V, the output stays in regulation up to I<sub>L</sub> = 25 mA. The error flag on pin 5 of the LP2951 sets low when the regulated output at pin 4 drops by about 5%. The LP2951 can be shutdown by taking pin 3 high; the LMC7660 can be shutdown by shorting pin 7 and pin 8.

The LP2951 can be reconfigured to an adjustable type regulator, which means the LMC7660 can give a regulated output from −2.0V to −10V dependent on the resistor ratios R1 and R2, as shown in Figure 22, V<sub>ref</sub> = 1.235V:

\[
V_{out} = V_{ref} \left( 1 + \frac{R1}{R2} \right)
\]  

(4)

![Figure 20. µPower Thermometer Spans 180°C, and Pulls Only 150 µA](image)

*For lower voltage operation, use Schottky rectifiers

![Figure 21. Regulated −5V with 200 µA Standby Current](image)
\[ V_{out} = V_{ref} \left(1 + \frac{R_1}{R_2}\right) \]

\( V_{ref} = 1.235V \)

*Low voltage operation

**Figure 22. LMC7660 and LP2951 Make a Negative Adjustable Regulator**
REVISION HISTORY

Changes from Revision B (April 2013) to Revision C

- Changed layout of National Data Sheet to TI format

Page 11
# PACKAGING INFORMATION

<table>
<thead>
<tr>
<th>Orderable Device</th>
<th>Status (1)</th>
<th>Package Type</th>
<th>Package Drawing</th>
<th>Pins</th>
<th>Package Qty</th>
<th>Eco Plan (2)</th>
<th>Lead/Ball Finish</th>
<th>MSL Peak Temp</th>
<th>Op Temp (°C)</th>
<th>Device Marking (4/5)</th>
<th>Samples</th>
</tr>
</thead>
<tbody>
<tr>
<td>LMC7660IM</td>
<td>NRND</td>
<td>SOIC</td>
<td>D</td>
<td>8</td>
<td>95</td>
<td>TBD</td>
<td>Call TI</td>
<td>Call TI</td>
<td></td>
<td>LMC7660IM</td>
<td>Samples</td>
</tr>
<tr>
<td>LMC7660IM/NOPB</td>
<td>ACTIVE</td>
<td>SOIC</td>
<td>D</td>
<td>8</td>
<td>95</td>
<td>Green (RoHS &amp; no Sb/Br)</td>
<td>CU SN</td>
<td>Level-1-260C-UNLIM</td>
<td>-40 to 85</td>
<td></td>
<td>LMC7660IM</td>
</tr>
<tr>
<td>LMC7660IMX</td>
<td>NRND</td>
<td>SOIC</td>
<td>D</td>
<td>8</td>
<td>2500</td>
<td>TBD</td>
<td>Call TI</td>
<td>Call TI</td>
<td></td>
<td>LMC7660IMX</td>
<td>Samples</td>
</tr>
<tr>
<td>LMC7660IMX/NOPB</td>
<td>ACTIVE</td>
<td>SOIC</td>
<td>D</td>
<td>8</td>
<td>2500</td>
<td>Green (RoHS &amp; no Sb/Br)</td>
<td>CU SN</td>
<td>Level-1-260C-UNLIM</td>
<td>-40 to 85</td>
<td></td>
<td>LMC7660IMX</td>
</tr>
<tr>
<td>LMC7660IN/NOPB</td>
<td>ACTIVE</td>
<td>PDIP</td>
<td>P</td>
<td>8</td>
<td>40</td>
<td>Green (RoHS &amp; no Sb/Br)</td>
<td>CU SN</td>
<td>Level-1-NA-UNLIM</td>
<td>-40 to 85</td>
<td></td>
<td>LMC7660IN</td>
</tr>
</tbody>
</table>

(1) The marketing status values are defined as follows:
- **ACTIVE**: Product device recommended for new designs.
- **LIFEBUY**: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
- **NRND**: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
- **PREVIEW**: Device has been announced but is not in production. Samples may or may not be available.
- **OBSOLETE**: TI has discontinued the production of the device.

(2) **RoHS**: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
- **RoHS Exempt**: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
- **Green**: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) **MSL, Peak Temp.** - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) **Lead/Ball Finish** - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.
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## TAPE AND REEL INFORMATION

### TAPE DIMENSIONS

<table>
<thead>
<tr>
<th>Dimension</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>A0</td>
<td>Dimension designed to accommodate the component width</td>
</tr>
<tr>
<td>B0</td>
<td>Dimension designed to accommodate the component length</td>
</tr>
<tr>
<td>K0</td>
<td>Dimension designed to accommodate the component thickness</td>
</tr>
<tr>
<td>W</td>
<td>Overall width of the carrier tape</td>
</tr>
<tr>
<td>P1</td>
<td>Pitch between successive cavity centers</td>
</tr>
</tbody>
</table>

### REEL DIMENSIONS

<table>
<thead>
<tr>
<th>Reel Diameter (mm)</th>
<th>Reel Width W1 (mm)</th>
<th>A0 (mm)</th>
<th>B0 (mm)</th>
<th>K0 (mm)</th>
<th>P1 (mm)</th>
<th>W (mm)</th>
<th>Pin1 Quadrant</th>
</tr>
</thead>
<tbody>
<tr>
<td>330.0</td>
<td>12.4</td>
<td>6.5</td>
<td>5.4</td>
<td>2.0</td>
<td>8.0</td>
<td>12.0</td>
<td>Q1</td>
</tr>
</tbody>
</table>

*All dimensions are nominal.*

### PACKAGE MATERIALS INFORMATION

<table>
<thead>
<tr>
<th>Device</th>
<th>Package Type</th>
<th>Package Drawing</th>
<th>Pins</th>
<th>SPQ</th>
<th>Reel Diameter (mm)</th>
<th>Reel Width W1 (mm)</th>
<th>A0 (mm)</th>
<th>B0 (mm)</th>
<th>K0 (mm)</th>
<th>P1 (mm)</th>
<th>W (mm)</th>
<th>Pin1 Quadrant</th>
</tr>
</thead>
<tbody>
<tr>
<td>LMC7660IMX</td>
<td>SOIC</td>
<td>D</td>
<td>8</td>
<td>2500</td>
<td>330.0</td>
<td>12.4</td>
<td>6.5</td>
<td>5.4</td>
<td>2.0</td>
<td>8.0</td>
<td>12.0</td>
<td>Q1</td>
</tr>
<tr>
<td>LMC7660IMX/NOPB</td>
<td>SOIC</td>
<td>D</td>
<td>8</td>
<td>2500</td>
<td>330.0</td>
<td>12.4</td>
<td>6.5</td>
<td>5.4</td>
<td>2.0</td>
<td>8.0</td>
<td>12.0</td>
<td>Q1</td>
</tr>
</tbody>
</table>
**TAPE AND REEL BOX DIMENSIONS**

*All dimensions are nominal*

<table>
<thead>
<tr>
<th>Device</th>
<th>Package Type</th>
<th>Package Drawing</th>
<th>Pins</th>
<th>SPQ</th>
<th>Length (mm)</th>
<th>Width (mm)</th>
<th>Height (mm)</th>
</tr>
</thead>
<tbody>
<tr>
<td>LMC7660IMX</td>
<td>SOIC</td>
<td>D</td>
<td>8</td>
<td>2500</td>
<td>367.0</td>
<td>367.0</td>
<td>35.0</td>
</tr>
<tr>
<td>LMC7660IMX/NOPB</td>
<td>SOIC</td>
<td>D</td>
<td>8</td>
<td>2500</td>
<td>367.0</td>
<td>367.0</td>
<td>35.0</td>
</tr>
</tbody>
</table>
NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

9. Board assembly site may have different recommendations for stencil design.
MECHANICAL DATA

P (R-PDIP-T8)  PLASTIC DUAL-IN-LINE PACKAGE

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS-001 variation BA.

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